

# **CBM2093**

## ***USB 2.0 Flash Disk Controller***

### **Wafer Specification**

---

Rev 1.0

**Chipsbank Technologies (Shenzhen) Co.,Ltd.**

7/F, Building No.12, Keji Central Road 2,  
Software Park, High-Tech Industrial Park, Shenzhen,  
P.R.China 518057

Tel: 0755-86169650-808

Fax: 0755-86169690

Email: [info@chipsbank.com](mailto:info@chipsbank.com)

URL: <http://www.chipsbank.com>

**Contained herein**

**Copyright by Chipsbank Technologies (Shenzhen) Co.,Ltd all rights reserved.**

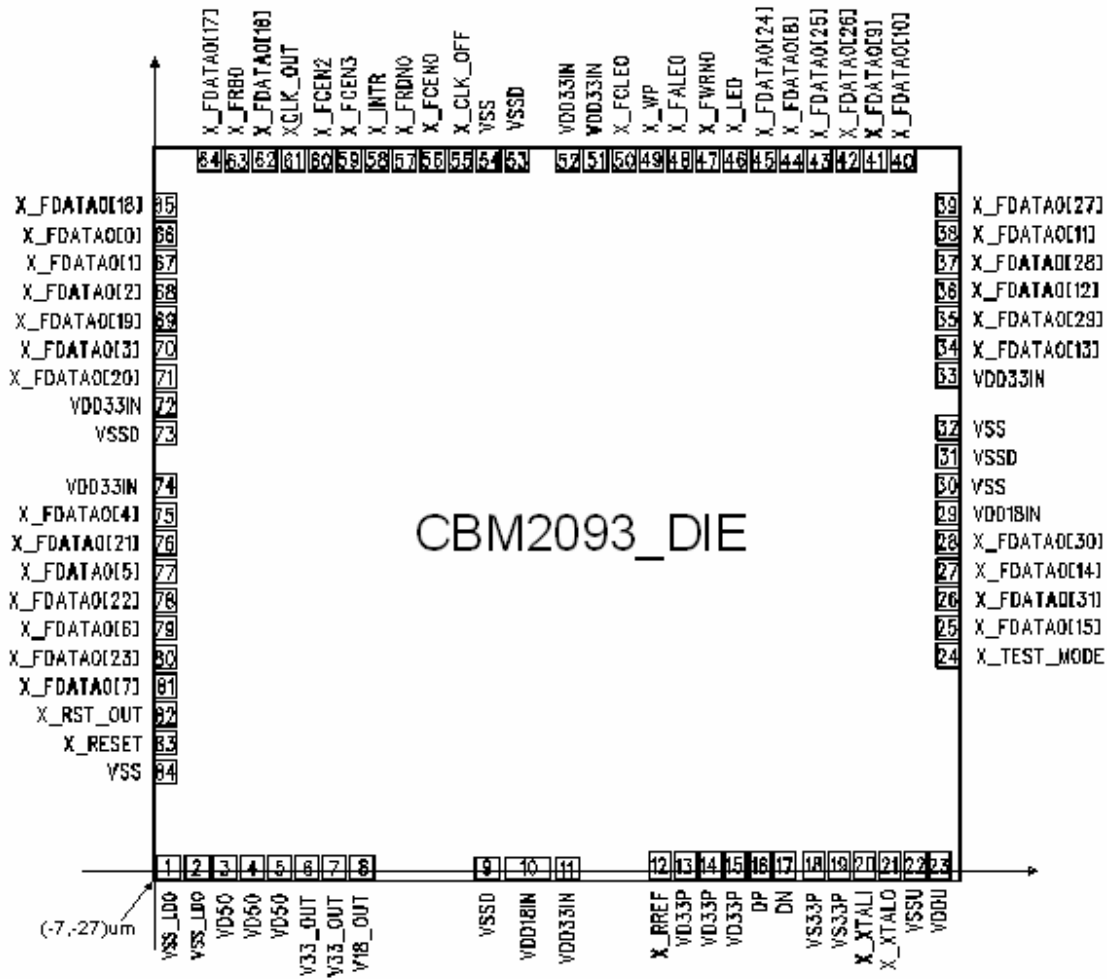
## Revision History

<b>Date</b>	<b>Rev No</b>	<b>Description</b>
2009-05-12	1.0	Initial release

## Contents

1	<i>PAD CONFIGURATION</i> .....	4
2	<i>DIE INFORMATION TABLE</i> .....	4
3	<i>PAD INFORMATION TABLE</i> .....	5
4	<i>COPYRIGHT NOTICE</i> .....	7

## 1 PAD Configuration



## 2 Die Information Table

Die Size	2268 x 2059 um
PAD Pitch	70 um
Typical PAD Size	66 x 60 um ( Pad10 is 128 x 60um , PAD12 ~ 23 are 60 x 76um )

### 3 PAD Information Table

NO.	Pad Name	Pad Position(um)		Remark
		X	Y	
1	VSS_LDO	39.238	9.681	Bottom
2	VSS_LDO	115.736	9.681	Bottom
3	VD50	192.238	9.681	Bottom
4	VD50	269.638	9.681	Bottom
5	VD50	346.138	9.681	Bottom
6	V33_OUT	422.64	9.681	Bottom
7	V33_OUT	499.138	9.681	Bottom
8	V18_OUT	575.639	9.681	Bottom
9	VSSD	923.652	6.975	Bottom
10	VDD18IN	1037.052	6.975	Bottom
11	VDD33IN	1146.852	6.975	Bottom
12	X_RREF	1404.018	14.987	Bottom
13	VD33P	1473.948	14.987	Bottom
14	VD33P	1543.878	14.987	Bottom
15	VD33P	1613.808	14.987	Bottom
16	DP	1683.738	14.987	Bottom
17	DN	1753.668	14.987	Bottom
18	VS33P	1833.588	14.987	Bottom
19	VS33P	1903.518	14.987	Bottom
20	X_XTALI	1973.448	14.987	Bottom
21	X_XTALO	2043.378	14.987	Bottom
22	VSSU	2113.308	14.987	Bottom
23	VDDU	2183.238	14.987	Bottom
24	X_TEST_MODE	2205.225	598.711	Right
25	X_FDATA0[15]	2205.225	677.952	Right
26	X_FDATA0[31]	2205.225	757.192	Right
27	X_FDATA0[14]	2205.225	836.433	Right
28	X_FDATA0[30]	2205.225	915.673	Right
29	VDD18IN	2205.225	994.914	Right
30	VSS	2205.225	1074.154	Right
31	VSSD	2205.225	1153.395	Right
32	VSS	2205.225	1232.636	Right
33	VDD33IN	2205.225	1378.517	Right
34	X_FDATA0[13]	2205.225	1457.757	Right
35	X_FDATA0[29]	2205.225	1536.998	Right
36	X_FDATA0[12]	2205.225	1616.238	Right
37	X_FDATA0[28]	2205.225	1695.479	Right
38	X_FDATA0[11]	2205.225	1774.719	Right
39	X_FDATA0[27]	2205.225	1853.96	Right
40	X_FDATA0[10]	2082.2	1978.425	Top
41	X_FDATA0[9]	2004.399	1978.425	Top
42	X_FDATA0[26]	1926.599	1978.425	Top
43	X_FDATA0[25]	1848.794	1978.425	Top
44	X_FDATA0[8]	1770.998	1978.425	Top
45	X_FDATA0[24]	1693.193	1978.425	Top

NO.	Pad Name	Pad Position(um)		Remark
		X	Y	
46	X_LED	1615.397	1978.425	Top
47	X_FWRN0	1537.597	1978.425	Top
48	X_FALE0	1459.796	1978.425	Top
49	X_WP	1381.995	1978.425	Top
50	X_FCLE0	1304.195	1978.425	Top
51	VDD33IN	1226.394	1978.425	Top
52	VDD33IN	1148.598	1978.425	Top
53	VSSD	1005.606	1978.425	Top
54	VSS	927.806	1978.425	Top
55	X_CLK_OFF	850.005	1978.425	Top
56	X_FCEN0	772.205	1978.425	Top
57	X_FRDN0	694.404	1978.425	Top
58	X_INTR	616.604	1978.425	Top
59	X_FCEN3	538.802	1978.425	Top
60	X_FCEN2	461.003	1978.425	Top
61	X_CLK_OUT	383.203	1978.425	Top
62	X_FDATA0[16]	305.402	1978.425	Top
63	X_FRB0	227.601	1978.425	Top
64	X_FDATA0[17]	149.801	1978.425	Top
65	X_FDATA0[18]	26.775	1853.748	Left
66	X_FDATA0[0]	26.775	1774.296	Left
67	X_FDATA0[1]	26.775	1694.844	Left
68	X_FDATA0[2]	26.775	1615.392	Left
69	X_FDATA0[19]	26.775	1535.94	Left
70	X_FDATA0[3]	26.775	1456.488	Left
71	X_FDATA0[20]	26.775	1377.036	Left
72	VDD33IN	26.775	1297.589	Left
73	VSSD	26.775	1218.141	Left
74	VDD33IN	26.775	1071.847	Left
75	X_FDATA0[4]	26.775	992.399	Left
76	X_FDATA0[21]	26.775	912.951	Left
77	X_FDATA0[5]	26.775	833.504	Left
78	X_FDATA0[22]	26.775	754.056	Left
79	X_FDATA0[6]	26.775	674.604	Left
80	X_FDATA0[23]	26.775	595.152	Left
81	X_FDATA0[7]	26.775	515.701	Left
82	X_RST_OUT_	26.775	436.248	Left
83	X_RESET_	26.775	356.796	Left
84	VSS	26.775	277.344	Left

## 4 Copyright Notice

Copyright by Chipsbank Technologies (Shenzhen) Co. Ltd. All Rights Reserved.

**Right to make changes** —Chipsbank Technologies (Shenzhen) Co., Ltd reserves the right to make changes in the products - including circuits, standard cells, and/or software - described or contained herein in order to improve design and/or performance. The information contained in this manual is provided for the general use by our customers. Our customers should be aware that the personal computer field is the subject of many patents. Our customers should ensure that they take appropriate action so that their use of our products does not infringe upon any patents. It is the policy of Chipsbank Technologies (Shenzhen) Co., Ltd. to respect the valid patent rights of third parties and not to infringe upon or assist others to infringe upon such rights.

This manual is copyrighted by Chipsbank Technologies (Shenzhen) Co., Ltd. You may not reproduce, transmit, transcribe, store in a retrieval system, or translate into any language, in any form or by any means, electronic, mechanical, magnetic, optical, chemical, manual, or otherwise, any part of this publication without the expressly written permission from Chipsbank Technologies (Shenzhen) Co.,Ltd